



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	10/24/2014
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	------	----------------------------	----------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EYE3*0158BG6	A	ZS1A	10/24/2014
Amount	UoM	Unit type	ST ECOPACK Grade	
25.20	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	3X3X0.86	8	gull wing	
Comment	Package: MSOP/TSSOP 8 BODY 3.00 PITCH 0.65; MD valid for LM2904ST, LM258AST, LM358AST, LM358ST			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EYE3*0158BG6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other Inorganic Material	0.718	mg	Supplier	Silicon Die	Si	7440-21-3		0.705	mg	981894	27976
Silicon Die				Supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	8357	238
Silicon Die				Supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.003	mg	4178	119
Silicon Die				Supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.004	mg	5571	159
Leadframe	Copper and its alloy	9.846	mg	Supplier	Alloy	Copper	7440-50-8		9.509	mg	965773	377341
Leadframe				Supplier	Alloy	Iron (2.1~2.6%)	7439-89-6		0.223	mg	22649	8849
Leadframe				Supplier	Alloy	Phosphorus (0.015~0.15%)	7723-14-0		0.002	mg	203	79
Leadframe				Supplier	Alloy	Zinc (0.05~0.20%)	7440-66-6		0.013	mg	1320	516
Leadframe				Supplier	Alloy	Silver (0.5~1.5%)	7440-22-4		0.099	mg	10055	3929
Die Attach	Other Organic Material	0.22	mg	Supplier	Glue	Silver (80 - 100%)	7440-22-4		0.169	mg	768182	6706
Die Attach				Supplier	Glue	methylene diacrylate	42594-17-2		0.037	mg	168182	1468
Die Attach				Supplier	Glue	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.004	mg	18182	159
Die Attach				Supplier	Glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.004	mg	18182	159
Die Attach				Supplier	Glue	Palladium (Pd)	7440-05-3		0.003	mg	13636	119
Die Attach				Supplier	Glue	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.003	mg	13636	119
Bonding Wire	Other Inorganic Material	0.31	mg	Supplier	Bonding Wire	Au	7440-57-5		0.31	mg	1000000	12302
Encapsulation	Other Organic Material	13.423	mg	Supplier	Molding Compound	Epoxy Resin-1 (0.5-6%)	Proprietary		0.402	mg	29949	15952
Encapsulation				Supplier	Molding Compound	Biphenyl epoxy resin	85954-11-6		0.201	mg	14974	7976
Encapsulation				Supplier	Molding Compound	Phenol resin (3-6%)	Proprietary		0.603	mg	44923	23929
Encapsulation				Supplier	Molding Compound	Silica (82-94%)	60676-86-0		11.691	mg	870968	463929
Encapsulation				Supplier	Molding Compound	Carbon Black (0.2%)	1333-86-4		0.027	mg	2011	1071
Encapsulation				Supplier	Molding Compound	Magnesium hydroxide	1309-42-8		0.402	mg	29949	15952
Encapsulation				Supplier	Molding Compound	Zinc hydroxide	20427-58-1		0.097	mg	7226	3849
Finishing	Other Inorganic Material	0.683	mg	Supplier	Connection coating	Tin	7440-31-5		0.683	mg	1000000	27103